

COPYRIGHT: (C)1999,JPO

?s pn=jp 5021520

S3 1 PN=JP 5021520

?t 3/6

3/6/1

04029820 **Image available**

IC MOUNTING METHOD

3/7/1

DIALOG(R)File 347:JAPIO

(c) 2001 JPO & JAPIO. All rts. reserv.

04029820 **Image available**

IC MOUNTING METHOD

PUB. NO.: 05-021520 [*JP 5021520* A]

PUBLISHED: January 29, 1993 (19930129)

INVENTOR(s): TAKENAKA TOSHIAKI

NISHII TOSHIHIRO

KISHIMOTO KUNIO

NAKAMURA SHINJI

APPLICANT(s): MATSUSHITA ELECTRIC IND CO LTD [000582] (A Japanese Company
or Corporation), JP (Japan)

APPL. NO.: 03-176615 [JP 91176615]

FILED: July 17, 1991 (19910717)

ABSTRACT

PURPOSE: To provide an IC mounting method by which stable electrical connection can be obtained by eliminating the problem of defective connection caused by the thrusting-up force of a thermally expanded IC chip when a liquid sealing resin filling up the gap between a circuit board and the IC chip is heated at the time of connecting the IC chip used for electronic equipment with the circuit board, such as a liquid crystal panel, etc.

CONSTITUTION: After a conductive bonding agent 4 is applied to the top sections of bumps (projecting contact) 3 formed on electrodes pads 2 on an IC chip 1 and connecting the chip 1 to terminal electrodes 6 on a circuit board 5 by positioning and press-contacting the chip 1 to and upon the electrodes 6 and hardening the bonding agent 4 by heating, the gap between the IC chip 1 and circuit board 5 is filled up with a sealing resin 7 and the resin 7 is hardened by heating while the chip 1 is pressed against the board 5 with a load stronger than the thrusting-up force of the thermally expanded chip 1 at the time of heating the resin 7 by using a pressurizing jig 8. Therefore, since the resin 7 is hardened while a load or pressure stronger than the thrusting-up force of the chip is applied, the occurrence of defective connection caused by the thrusting-up force of the chip 1 can be prevented.